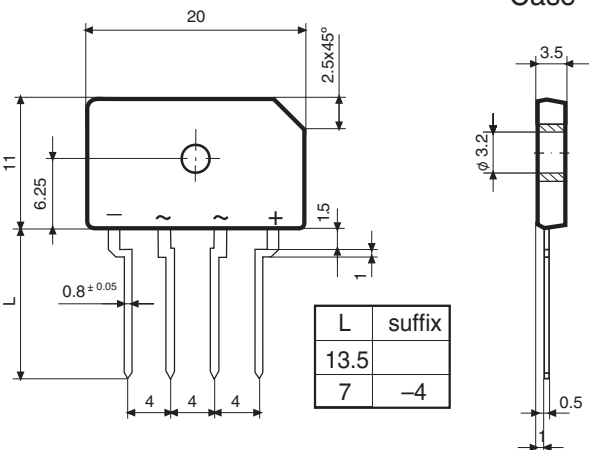


## 1.5 Amp. Glass Passivated Bridge Rectifier

<p>Dimensions in mm.</p>  <p><b>• Mounting Instructions</b></p> <ul style="list-style-type: none"> <li>• High temperature soldering guaranteed: 260 °C – 10 sc.</li> <li>• Recommended mounting torque: 8 Kg.cm.</li> </ul>	<p>Plastic Case</p> <p>Voltage 50 to 1000 V.</p> <p>Current 1.5 A.</p> <p><b>HYPERECTIFIER</b>®</p> <ul style="list-style-type: none"> <li>• Glass Passivated Junction Chips.</li> <li>• UL recognized under component index file number E320541.</li> <li>• Lead and polarity identifications.</li> <li>• Case: Molded Plastic.</li> <li>• Ideal for printed circuit board (P.C.B.).</li> <li>• The plastic material carries U/L recognition 94 V-O.</li> </ul>
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### Maximum Ratings, according to IEC publication No. 134

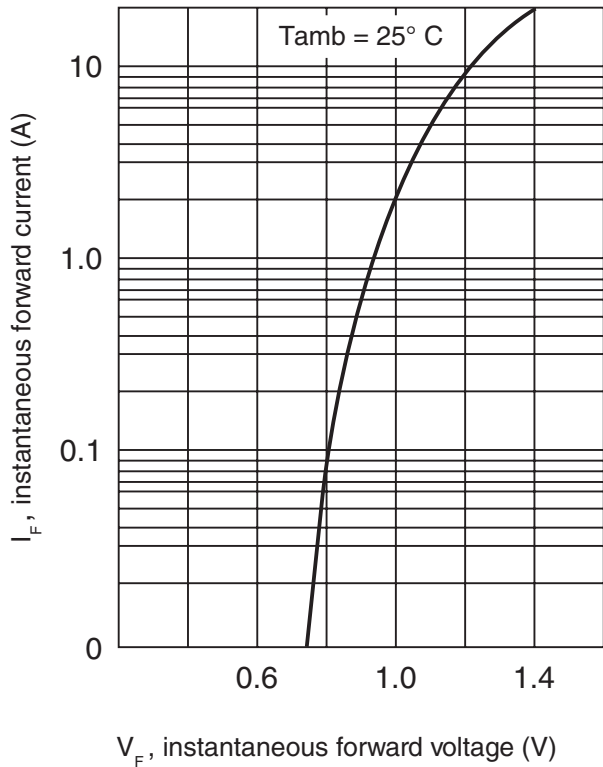
		FBI1.5A 4S1	FBI1.5B 4S1	FBI1.5D 4S1	FBI1.5G 4S1	FBI1.5J 4S1	FBI1.5K 4S1	FBI1.5M 4S1
$V_{RRM}$	Peak recurrent reverse voltage (V)	50	100	200	400	600	800	1000
$V_{RMS}$	Maximum RMS voltage (V)	35	70	140	280	420	560	700
$I_{F(AV)}$	Max. Average forward current with heatsink without heatsink	4.0 A at 65 °C 1.5 A at 25 °C						
$I_{FSM}$	8.3 ms. peak forward surge current (Jedec Method)	50 A						
$I^2t$	Rating for fusing (t < 8.3 ms.)	10 A <sup>2</sup> sec						
$V_{DIS}$	Dielectric strength (terminals to case, AC 1 min.)	1500 V						
$T_j$	Operating temperature range	- 55 to + 150 °C						
$T_{stg}$	Storage temperature range	- 55 to +150 °C						

### Electrical Characteristics at Tamb = 25°C

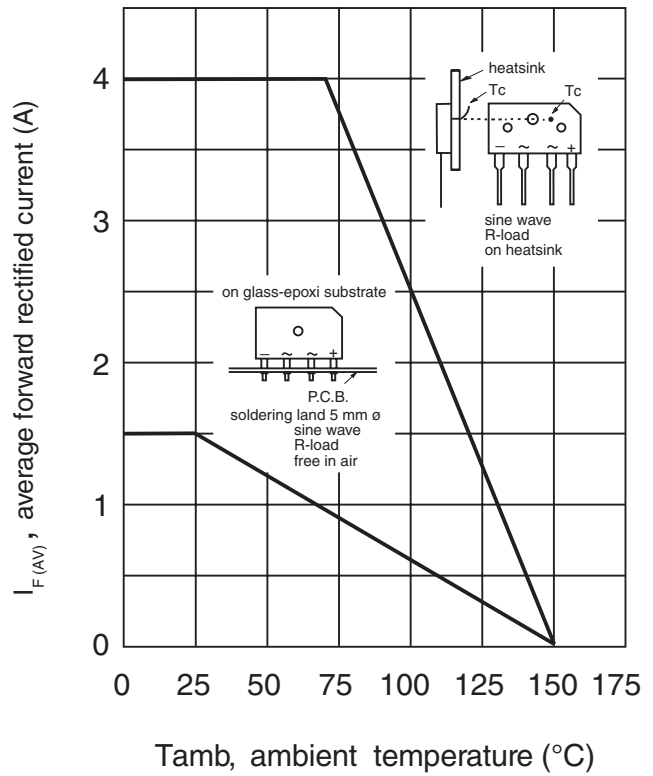
$V_F$	Max. forward voltage drop per element at $I_F = 1$ A	1.0 V
$I_R$	Max. reverse current per element at $V_{RRM}$	5 $\mu$ A
$R_{th(j-c)}$	MAXIMUM THERMAL RESISTANCE Junction-Case. With Heatsink.	12 °C/W
$R_{th(j-a)}$	Junction-Ambient. Without Heatsink.	45 °C/W

**Characteristic Curves**

TYPICAL FORWARD CHARACTERISTIC



FORWARD CURRENT DERATING CURVE



MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT

